METHOD OF DICING SEMICONDUCTOR WAFER INTO CHIPS, AND APPARATUS USING THIS METHOD

ABSTRACT OF THE DISCLOSURE

The invention relates to a semiconductor wafer dicing method of dicing a semiconductor wafer along parting lines into chips. The semiconductor wafer in which parting lines along which the semiconductor wafer is diced into chips are formed is held by an adhesive tape. By radially drawing the adhesive tape in a state where the chips in the semiconductor wafer are not parted from each other, the chips are parted from each other and clearances among the chips are extended.

(Fig. 2)